12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260818002.1	PCN Issued	August 19, 2026
Qualification of additional Assembly sites for select UxQFN device		Sample request deadline:	October 18, 2026
		Estimated 1st ship date:	November 17, 2026
Sample requests received after** October 18, 2026 will not be supported.**			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction information are as follows:

UxQFN Build sites	
Assembly Sites	ASEN, CARZ, JCETJY, CLARK, CDAT, TIEMA
Mount Compound	SID#1500257101
	4221460
	SID#1500131111-1
	SID#438933
	SID#439825
	S#120402001600
	SID#1500094113
	4226215
Mold Compound	S#120903005409
	SID#1801512111
	SID#439086
	SID#441141
	4222198
Wire	Au, Cu (0.7mil, 0.8mil)
Lead Frame Finish	NiPdAu

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet (SDP) for more details on the changes.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474

	☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASEN	ASN	CHN	Suzhou
CARZ	CSZ	CHN	Jiangsu
JCETJY	JCE	CHN	Jiangyin
CLARK	QAB	PHL	Angeles city, Pampanga
TIEM	CU6	MYS	Melaka
CDAT	CDA	CHN	Chengdu

Sample product shipping label (not actual product label):

Products Affected:

SN74LVC1G00DSF2	SN74LVC1G08DSF2	SN74LVC1G332DSF2
SN74LVC1G00DSFR	SN74LVC1G11DSFR	SN74LVC1G332DSFR
SN74LVC1G02DSF2	SN74LVC1G125DSFR	SN74LVC1G34DSFR
SN74LVC1G02DSFR	SN74LVC1G126DSFR	SN74LVC1G38DSFR
SN74LVC1G04DSF2	SN74LVC1G17DSFR	SN74LVC1G58DSF2
SN74LVC1G06DSFR	SN74LVC1G240DSFR	SN74LVC1G58DSFR
SN74LVC1G07DSF2	SN74LVC1G27DSFR	
SN74LVC1G07DSFR	SN74LVC1G32DSF2	

UxQFN Qualification Report

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	CLARK SN74AXC2T45DTM LSF0102DTM LSF0002DTQ LSF0101DTQ	CDAT ADS1115IRUG TLV70732DQN TMAG5231H1DQDMR SN74LVC1G3157DSFR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 150C	1000 hours	3/231/0	-
HTSL	High Temp. Storage Bake 170C	420 hours	-	3/231/0
UHAST	Unbiased HAST,130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	CARZAT SN74AXC2T45DTM	TIEMA LM43112SN LP8549B1ASPX03 LP3971SQ-D510/NOPB DS99R421ISNG2G
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	-
AC	Autoclave 121C	96 hours	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	ASEN SN74AXC2T45DTM SN74AXC1T45DTQ	JCET TPD4E05U06DQAR TLV9064IRUCR
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	3/231/0	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	pass

SN74AXC2T45DTM, SN74AXC1T45DTQ, LSF0102DTM, LSF0002DTQ, LSF0101DTQ and LP3971SQ-D510/NOPB, ADS1115IRUG, TLV70732DQN, TMAG5231H1DQDMR, TPD4E05U06DQAR, SN74LVC1G3157DSFR are qualified at MSL1. LM43112SN, LP8549B1ASPX03, TLV9064IRUCR are qualified at MSL2 and DS99R421ISNG2G qualified at MSL3.
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable
- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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